

Pad printing on rigid and flexible surfaces (Technion)

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This invention relates to the printing of micrometer or nanometer scale patterns using a modified pad printing apparatus. The device uses a printing plate prepared from a silicon wafer and a printing pad combined from one rubber standard pad and one Polydimethylsiloxane (PDMS) membrane or stamp as a sub pad. This invention improves upon the current methods by offering a more cost efficient solution without the limitation of optical diffraction or rubber pad abrasion. The simplicity of this improved method allows for larger volume productions that may be relevant by pad printing manufacturers, solar cell manufactures, EMI/RFI optical object shielding, and more.

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